TAPE ADHERING METHOD AND TAPE ADHERING APPARATUS

ABSTRACT OF THE DISCLOSURE

A method and an apparatus for adhering a tape (3) on a wafer (20) are disclosed. The wafer is supported on a table (31), and the tape is supplied, between a tape adhering surface (20') and a tape adhering unit (46), from a tape supply unit (42). The table is moved toward the tape adhering unit, whereby the tape adhering surface of the wafer on the table is pressed against the tape adhering unit through the tape with a force (F). Further, the tape adhering unit is moved from one end (28) to the other end (29) of the wafer in parallel to the tape adhering surface. The pressure (P) under which the tape adhering surface is in contact with the tape adhering unit through the tape is kept substantially uniform while the tape adhering unit moves from one end to the other end of the wafer. As a result, the pressure on the wafer is accurately equalized in spite of the movement of the tape adhering unit.

FIG. 2